



# Wireless Bipolar Power Transistor, 150W 850 - 960 MHz

PH0810-150

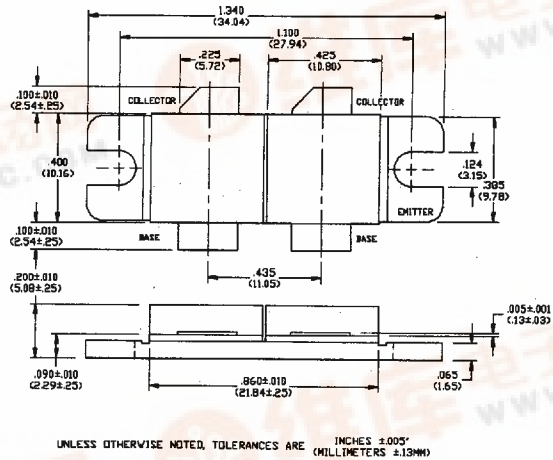
V2.01

## Features

- Designed for Linear Amplifier Applications
- Class AB: -32 dBc Typ 3rd IMD at 150 Watts PEP
- Common Emitter Configuration
- Internal Input and Output Impedance Matching
- Diffused Emitter Ballasting

## Absolute Maximum Ratings at 25°C

Parameter	Symbol	Rating	Units
Collector-Base Voltage	$V_{CBO}$	60	V
Collector-Emitter Voltage	$V_{CES}$	60	V
Emitter-Base Voltage	$V_{EB0}$	3.0	V
Collector Current	$I_C$	25	A
Total Power Dissipation	$P_{TOT}$	250	W
Junction Temperature	$T_J$	200	°C
Storage Temperature	$T_{STG}$	-55 to +150	°C
Thermal Resistance	$\theta_{JC}$	0.7	°C/W



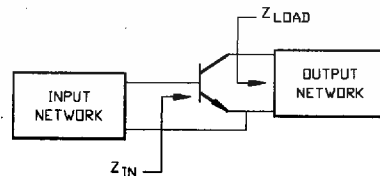
## Electrical Characteristics at 25°C

Parameter	Symbol	Min	Max	Units	Test Conditions
Collector-Emitter Breakdown Voltage	$BV_{CES}$	60	-	V	$I_C=50\text{ mA}^*$
Collector-Emitter Leakage Current	$I_{CES}$	-	10.0	mA	$V_{CE}=26.0\text{ V}^*$
Collector-Emitter Breakdown Voltage	$BV_{CEO}$	24	-	V	$I_C=100\text{ mA}^*$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	3.0	-	V	$I_B=50\text{ mA}^*$
DC Forward Current Gain	$h_{FE}$	15	120	-	$V_{CE}=5.0\text{ V}, I_C=1.0\text{ A}^*$
Power Gain	$G_p$	10	-	dB	$V_{CC}=26\text{ V}, I_{CO}=300\text{ mA}, P_{OUT}=150\text{ W PEP}, F=900\text{ MHz}, \Delta F=100\text{ kHz}$
Collector Efficiency	$\eta_C$	35	-	%	$V_{CC}=26\text{ V}, I_{CO}=300\text{ mA}, P_{OUT}=150\text{ W PEP}, F=900\text{ MHz}, \Delta F=100\text{ kHz}$
Input Return Loss	RL	10	-	dB	$V_{CC}=26\text{ V}, I_{CO}=300\text{ mA}, P_{OUT}=150\text{ W PEP}, F=900\text{ MHz}, \Delta F=100\text{ kHz}$
Load Mismatch Tolerance	VSWR-T	-	5.0:1	-	$V_{CC}=26\text{ V}, I_{CO}=300\text{ mA}, P_{OUT}=150\text{ W PEP}, F=900\text{ MHz}, \Delta F=100\text{ kHz}$
3rd Order IMD	$IMD_3$	-	-28	dBc	$V_{CC}=26\text{ V}, I_{CO}=300\text{ mA}, P_{OUT}=150\text{ W PEP}, F=900\text{ MHz}, \Delta F=100\text{ kHz}$

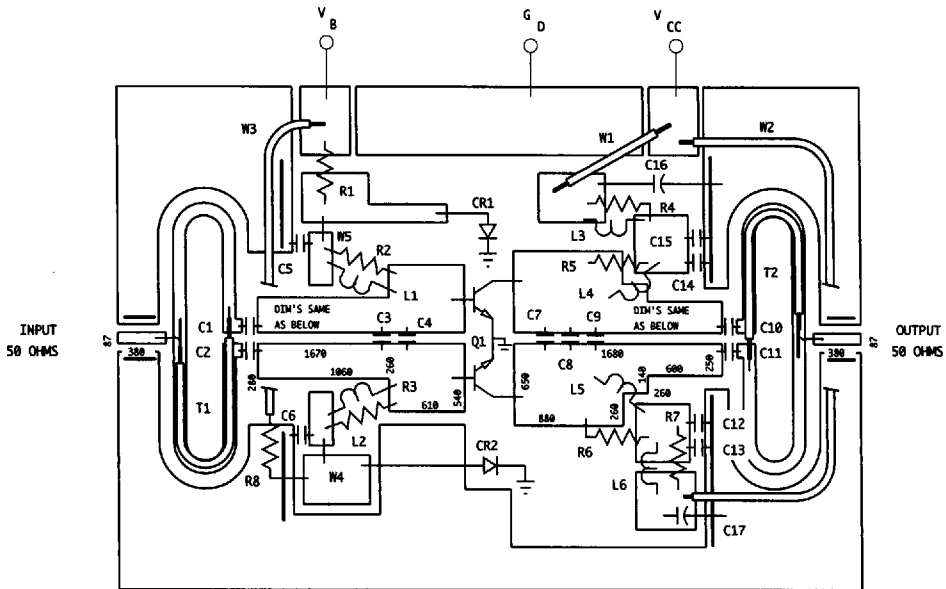
\* Per Side

## Typical Optimum Device Impedances

F(MHz)	$Z_{in}(\Omega)$	$Z_{LOAD}(\Omega)$
850	$2.2 + j6.0$	$3.3 - j5.4$
900	$3.5 + j5.6$	$3.4 - j5.0$
960	$3.6 + j4.0$	$2.3 - j5.2$



RF Test Fixture



PARTS LIST

C9	.7pF 100 VDC CHIP ATC TYPE B
C7 C8	3.6pF 100 VDC CHIP ATC TYPE B
C4	6.2pF 100 VDC CHIP ATC TYPE B
C3	26pF 100 VDC CHIP ATC TYPE B
C1 C2 C10 C11	43pF 100 VDC CHIP ATC TYPE B
C5 C6 C12 C14	100pF 100 VDC CHIP ATC TYPE B
C13 C15	5000pF 100 VDC CHIP ATC TYPE B
C16 C17	50uF 50 VOLTS
CR1 CR2	DIODE JXS417
L3 L6	7 TURNS OF NO. 18 AWG ON .150" DIA
L1 L2	11 TURNS OF NO. 18 AWG ON .150" DIA
L4 L5	11 TURNS OF NO. 18 AWG ON .100" DIA
Q1	PH0810-150
R2 R3 R4 R7	.47 OHM .5 WATT
R1 R5 R6 R8	.47 OHM 1 WATT
T1 T2	50 OHM SEMI RIGID COAX 2.20" X .088" OD
W1 W2 W3	NO. 16 AWG TEFLON WIRE
W4, W5	NO. 16 AWG JUMPER
BOARD MATERIAL	TEFLON GLASS, .031" THICK, Er = 2.54

Specifications Subject to Change Without Notice.